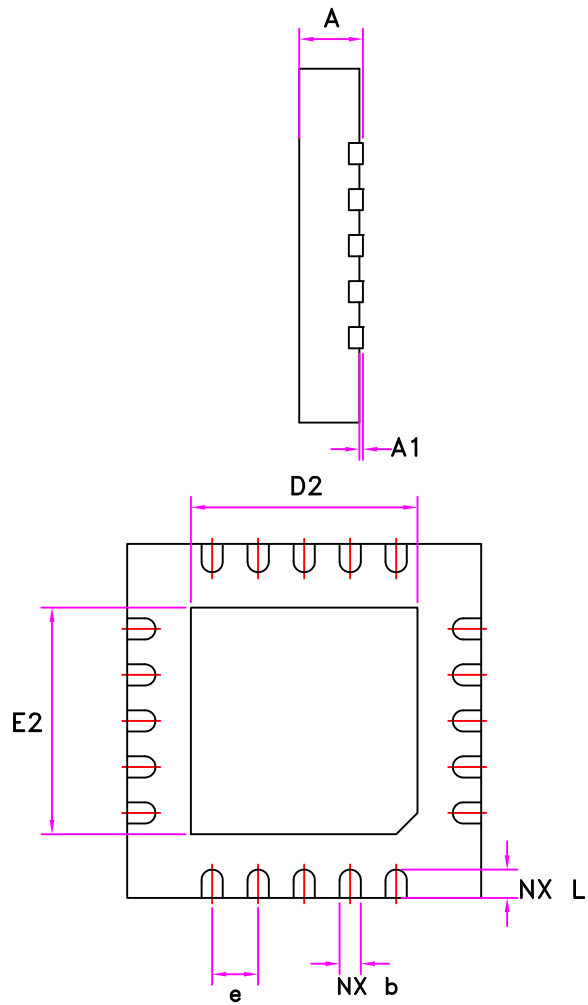
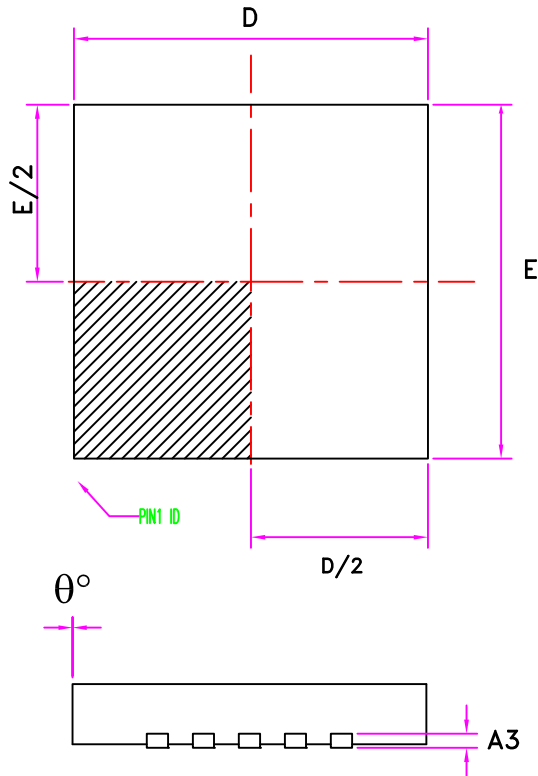


**5X5 MM QLMP**  
**QUAD LEADLESS MOLDED PACKAGE**

**PACKAGE INFORMATION (AS11xx)**



JEDEC#	NOT APPLICABLE			
TYPE	20 lead			
Dimension	mm		mils	
SYMBOL	Min	Max	Min	Max
A	0.85	0.95	33.46	37.40
A1	0	0.05	0	1.97
A3	0.175	0.225	6.89	8.86
D	4.9	5.1	192.91	200.79
E	4.9	5.1	192.91	200.79
D2	3.15	3.25	124.02	127.95
E2	3.15	3.25	124.02	127.95
e	0.65BSC		25.59BSC	
NX b	0.25	0.35	9.84	13.78
NX k	---	---	---	---
NX L	0.35	0.45	13.78	17.72
$\theta^\circ$	0°	4°	0°	4°
ND	5			
NE	5			

**NOTES**

1. SPADE WIDTH, LEAD WIDTH AND LEAD THICKNESS EXCLUSIVE OF SOLDER PLATE
2. PACKAGE OUTLINE EXCLUSIVE OF MOLD FLASHES AND BURR DIMENSIONS
3. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS. COPLANARITY SHALL NOT EXCEED 0.08mm.
4. WARPAGE SHALL NOT EXCEED 0.10mm.
5. THE TERMINAL #1 IDENTIFIER AND TERMINAL NUMBERING CONVENTION SHALL CONFORM TO JESD 95-1 SPP-012. DETAILS OF TERMINAL #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE TERMINAL#1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE.
6. ND AND NE REFER TO THE NUMBER OF TERMINALS ON EACH D AND E SIDE RESPECTIVELY.

PREPARED BY	XXX
CHECKED BY	XXX
APPROVED BY	XXX

REF. NO.	DIM-QLMP-5X5
REV. NO.	0
DATE	31.01.08

**AKROS SILICON**  
**USA**

